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REMARKS

Claims 24-37 are now pending in this application. Claims 1-23 have been cancelled without prejudice or disclaimer. Reconsideration of this application is requested.

Applicants affirm the election of the invention of Group I as defined in the outstanding Office action. Applicants reserve the right to file one or more divisional applications directed to one or more non-elected inventions as defined in the Office action.

The objection to the drawings and the rejection of claims 1-18 under 35 U.S.C. § 112 second paragraph are moot in view of the cancellation of claims 1-23 in favor of new claims 24-37, which meet all requirements of definiteness and which are fully supported by Figs. 1-4 as originally filed. Accordingly, withdrawal of the drawing objection and the indefiniteness rejection are requested.

The rejection of claims 1, 3, 4, 9-11 and 13 as being anticipated by Patel, the rejection of claims 1, 3, 4, 6-8, 11, 13-15, 17 and 18 as being anticipated by Hodge et al., the rejection of claim 5 as being obvious over Patel, and the rejection of claim 12 as being obvious over Patel or Hodge, are respectfully traversed to the extent that these grounds of rejection may be applied to claims 24-37 now pending in the application.

Patel discloses a heat dissipating assembly for extracting and dissipating heat from a heat-generating semiconductor device, such as transistor chip 14. The chip 14 is encapsulated between a ceramic header 15 and a metal cover assembly 16-17. The chip 14 is connected to a circuit board 11 via wires 19 connected to terminal leads 18. The encapsulation is held inside a metal holding member 20 between a lower shelf 21 and a metal ferrule 24, which rests on an upper shelf 25 of the holding member 20. Heat generated by the transistor chip 14 is channeled through the holding member 20 to a heat radiating member 12, which contacts the holding member 20 at thermal connection points 35.

Contrary to the present invention as recited in independent claims 24 and 37, Patel fails to disclose or suggest an electronic assembly having a radiographic sensor device, circuit board, thermal channel device, and heat sink structure as specifically set forth therein.

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Hodge et al. discloses a microelectronic circuit chip carrier for an IC chip 2, wherein the chip 2 is mounted on a top surface of a thermally conductive member 4 via a mounting material 6. The member 4 rests in a carrier 8 that in turn sits on a printed circuit board 10. The member 4 is attached to a heat sinking nut 16 on an opposite side of the PCB 10. Contrary to the present invention as recited in independent claims 24 and 37, Hodge also fails to disclose or suggest an electronic assembly having a radiographic sensor device, circuit board, thermal channel device, and heat sink structure as specifically set forth therein.

Consequently, neither Patel nor Hodge anticipates or renders obvious the invention as set forth in claims 24-37. The cited Dailey et al. and Pawlak et al. patents, assigned to the same assignee herein, have been reviewed and are not seen to be relevant to the patentability of the present invention as claimed.

Conclusion

In view of the foregoing, favorable reconsideration of this application and the issuance of a Notice of Allowance are earnestly solicited.

Please charge any fee or credit any overpayment pursuant to 37 CFR 1.16 or 1.17 to Deposit Account No. 02-2135.

RESPECTFULLY SUBMITTED,					
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